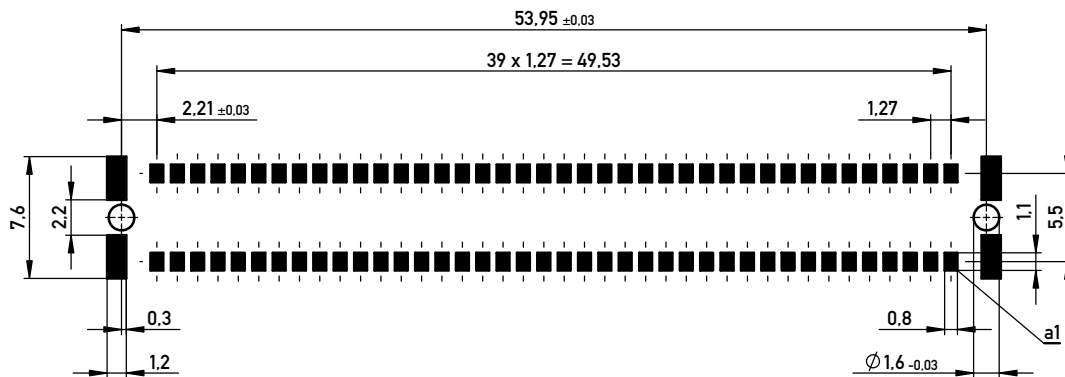


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



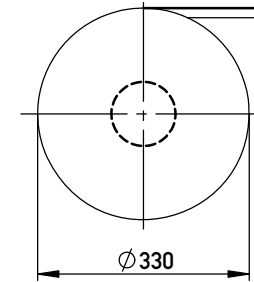
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

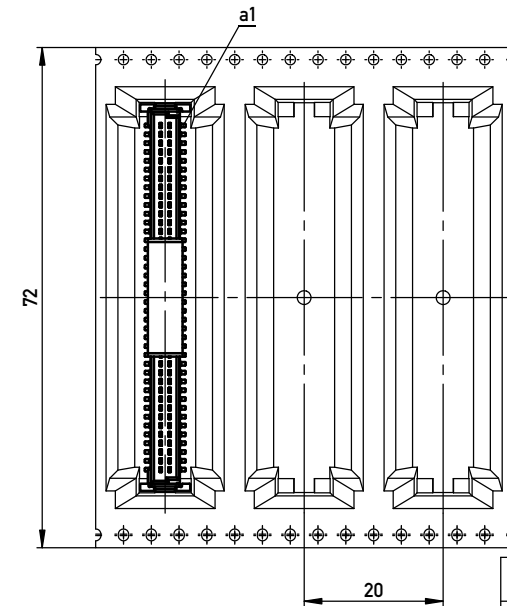
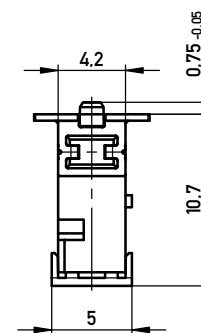
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 250 Stück
Packaging unit: 250 pcs



Abspulrichtung - Reel off Direction



BA 8-23 - hohe Bauhöhe
type 8-23 - High Profile

Information:	Tolerances	 All Dimensions in mm	Scale	3:1
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Subject to modification without prior notice. Drawing will not be updated.		www.ERNI.com		234210
e	26.06.2015	Class		SMCQ
Index	Date			A3

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